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(54) Title: METHOD OF SOLDERING OR BRAZING ARTICLES HAVING SURFACES THAT ARE DIFFICULT TO BOND

Provide articles having	NA
Provide articles having bonding surfaces	
J	·
Dispose universal solder	
or braze between	NB
bonding surfaces	
V	<u>.</u>
Wet the surfaces with	
solder and bond, under	NC
substantially oxygen-free	
conditions.	
	<u>l</u>

(57) Abstract: Applicant has discovered that articles comprising inorganic surfaces that are difficult to bond can be more effectively soldered or brazed with a solder or braze containing rare earth elements where the rare earth (RE) elements are substantially kept from contact with air at soldering temperatures, i.e. the RE elements are exposed to air for no more than a few seconds at soldering temperature. This can be efficiently accomplished in several ways. The result is efficient, strong bonding of materials previously considered difficult to bond.



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